

BSZ900N15NS3 G-VB Datasheet

N-Channel 150 V (D-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	150
$R_{DS(on)}$ (Ω) at $V_{GS} = 10$ V	0.035
Q_g typ. (nC)	8.5
I_D (A)	25.5 ^a
Configuration	Single

FEATURES

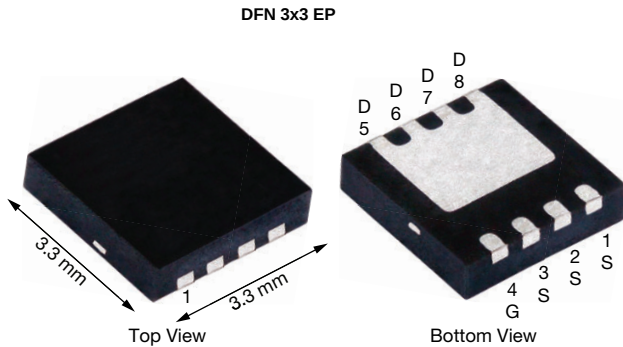
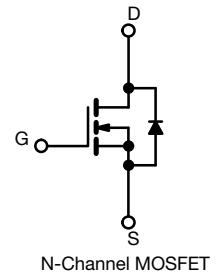
- Trench Cell optimizes balance of $R_{DS(on)}$, Q_g , Q_{sw} , and Q_{oss}
- 100 % R_g and UIS tested



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Primary side switching
- Synchronous rectification
- DC/DC converter
- Motor drive control
- Load switch



ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-source voltage	V_{DS}	150	V
Gate-source voltage	V_{GS}	± 20	
Continuous drain current ($T_J = 150$ °C)	I_D	$T_C = 25$ °C	A
		$T_C = 70$ °C	
		$T_A = 25$ °C	
		$T_A = 70$ °C	
Pulsed drain current ($t = 100$ μ s)	I_{DM}	50	
Continuous source-drain diode current	I_S	$T_C = 25$ °C	A
		$T_A = 25$ °C	
Single pulse avalanche current	I_{AS}	20	
Single pulse avalanche energy	E_{AS}	20	mJ
Maximum power dissipation	P_D	$T_C = 25$ °C	W
		$T_C = 70$ °C	
		$T_A = 25$ °C	
		$T_A = 70$ °C	
Operating junction and storage temperature range	T_J, T_{stg}	-55 to +150	°C
Soldering recommendations (peak temperature) ^c		260	

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient ^b	R_{thJA}	20	25	°C/W
Maximum junction-to-case (drain)	R_{thJC}	1.5	1.9	

Notes

- $T_C = 25$ °C
- Surface mounted on 1" x 1" FR4 board
- $t = 10$ s
- The DFN3x3 package is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- Maximum under steady state conditions is 65 °C/W

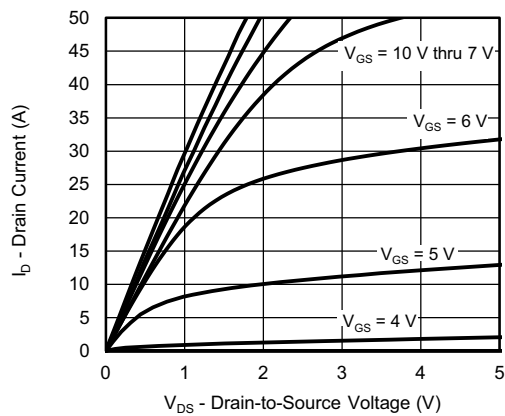
SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	150	-	-	V	
V _{DS} temperature coefficient	ΔV _{DS} /T _J	I _D = 250 mA	-	92	-	mV/°C	
V _{GS(th)} temperature coefficient	ΔV _{GS(th)} /T _J	I _D = 250 μA	-	-7.1	-		
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	2	-	4	V	
Gate-source leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V	-	-	100	nA	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 150 V, V _{GS} = 0 V	-	-	1	μA	
		V _{DS} = 150 V, V _{GS} = 0 V, T _J = 70 °C	-	-	15		
On-state drain current ^a	I _{D(on)}	V _{DS} ≤ 10 V, V _{GS} = 10 V	20	-	-	A	
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 7 A	-	0.035	-	Ω	
Forward transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 7 A	-	16	-	S	
Dynamic ^b							
Input capacitance	C _{iss}	V _{DS} = 75 V, V _{GS} = 0 V, f = 1 MHz	-	550	-	pF	
Output capacitance	C _{oss}		-	120	-		
Reverse transfer capacitance	C _{rss}		-	6	-		
Total gate charge	Q _g	V _{DS} = 75 V, V _{GS} = 10 V, I _D = 7 A	-	10.85	22	nC	
Gate-source charge	Q _{gs}	V _{DS} = 75 V, V _{GS} = 7.5 V, I _D = 7 A	-	8.5	13		
Gate-drain charge	Q _{gd}		-	3	-		
Output charge	Q _{oss}		-	3	-		
Gate resistance	R _g	V _{DS} = 75 V, V _{GS} = 0 V	-	27.7	42	Ω	
Turn-on delay time	t _{d(on)}	f = 1 MHz	0.24	1.2	2.4	ns	
Rise time	t _r	V _{DD} = 75 V, R _L = 13.4 Ω, I _D ≅ 5.6 A, V _{GEN} = 10 V, R _g = 1 Ω	-	18	36		
Turn-off delay time	t _{d(off)}		-	6	12		
Fall time	t _f		-	30	60		
Turn-on delay time	t _{d(on)}		-	9	18		
Rise time	t _r	V _{DD} = 75 V, R _L = 13.4 Ω, I _D ≅ 5.6 A, V _{GEN} = 7.5 V, R _g = 1 Ω	-	20	40		
Turn-off delay time	t _{d(off)}		-	8	16		
Fall time	t _f		-	25	50		
			-	11	22		
Drain-Source Body Diode Characteristics							
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	54.8		A
Pulse diode forward current	I _{SM}		-	-	50		
Body diode voltage	V _{SD}	I _S = 5.6 A, V _{GS} = 0 V	-	0.8	1.2		V
Body diode reverse recovery time	t _{rr}	I _F = 5.6 A, di/dt = 100 A/μs, T _J = 25 °C	-	60	120	ns	
Body diode reverse recovery charge	Q _{rr}		-	133	266	nC	
Reverse recovery fall time	t _a		-	50	-	ns	
Reverse recovery rise time	t _b		-	10	-		

Notes

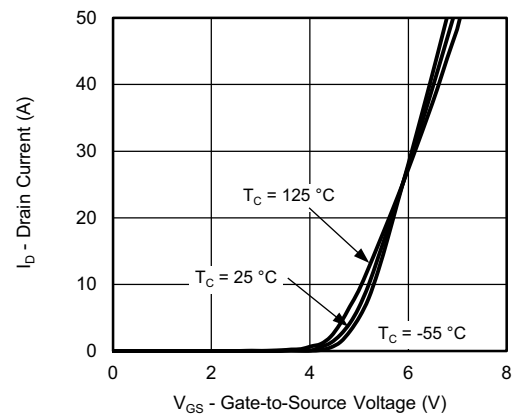
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
 b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

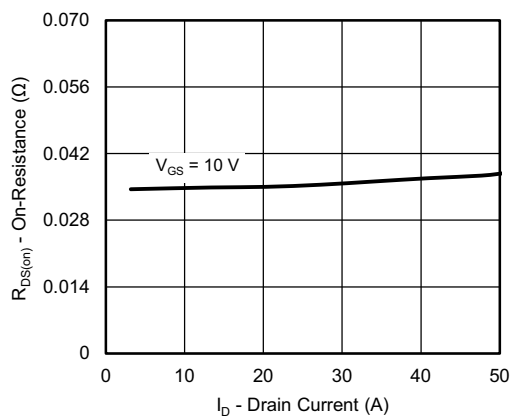
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



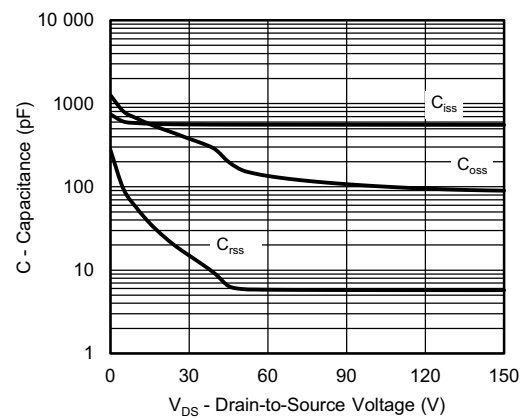
Output Characteristics



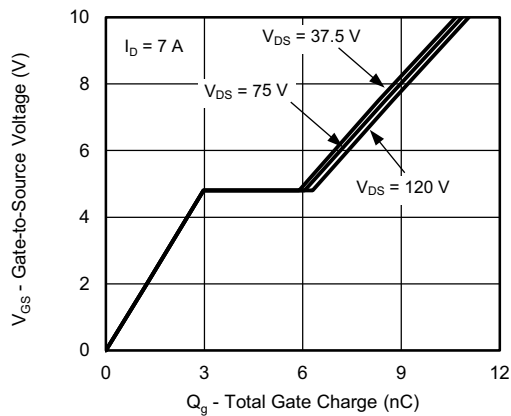
Transfer Characteristics



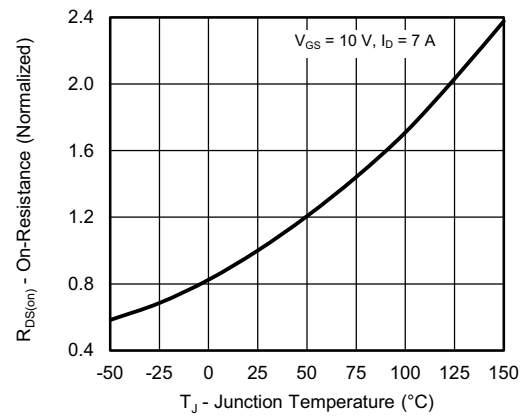
On-Resistance vs. Drain Current and Gate Voltage



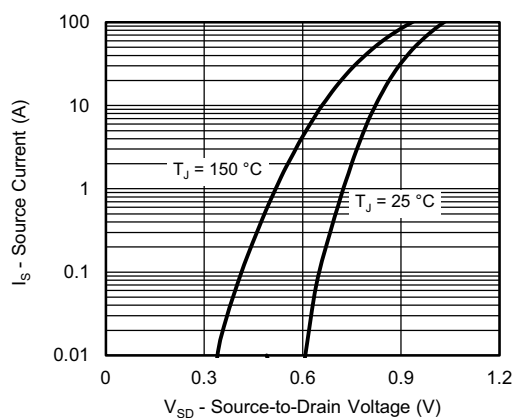
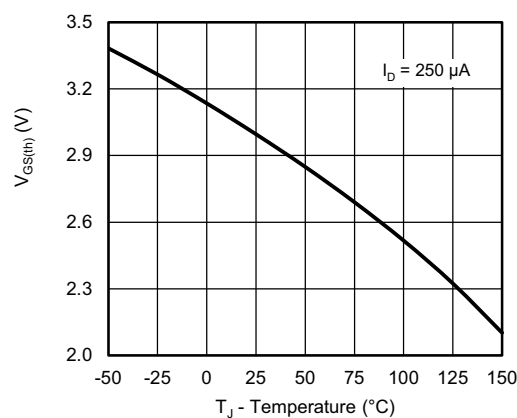
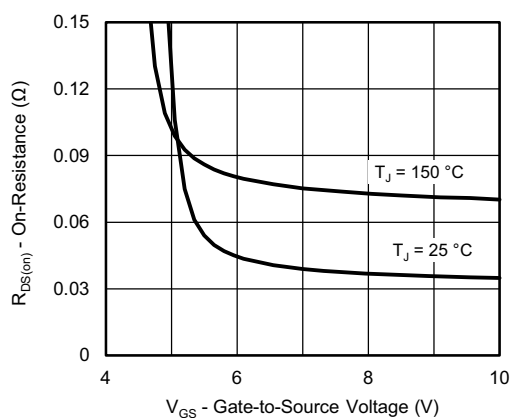
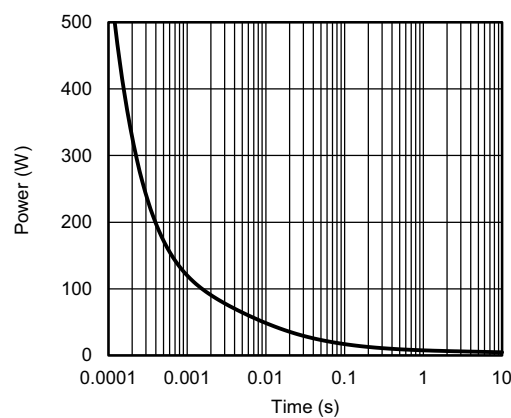
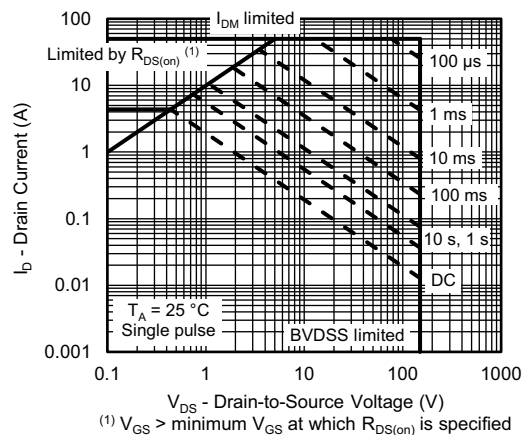
Capacitance

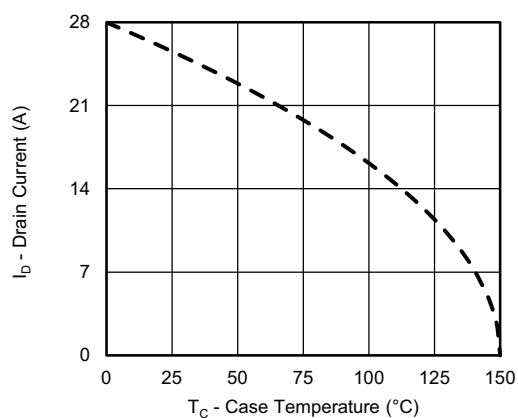
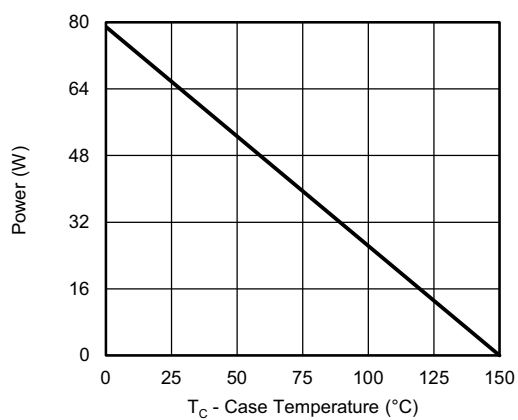
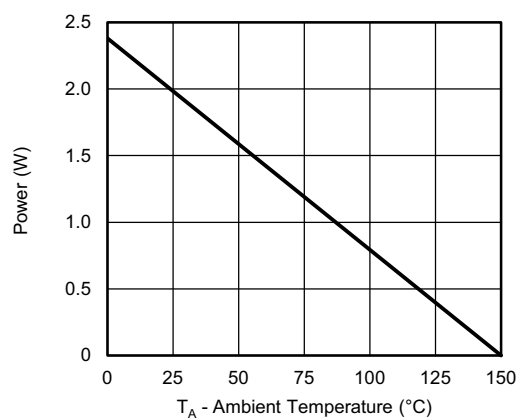


Gate Charge

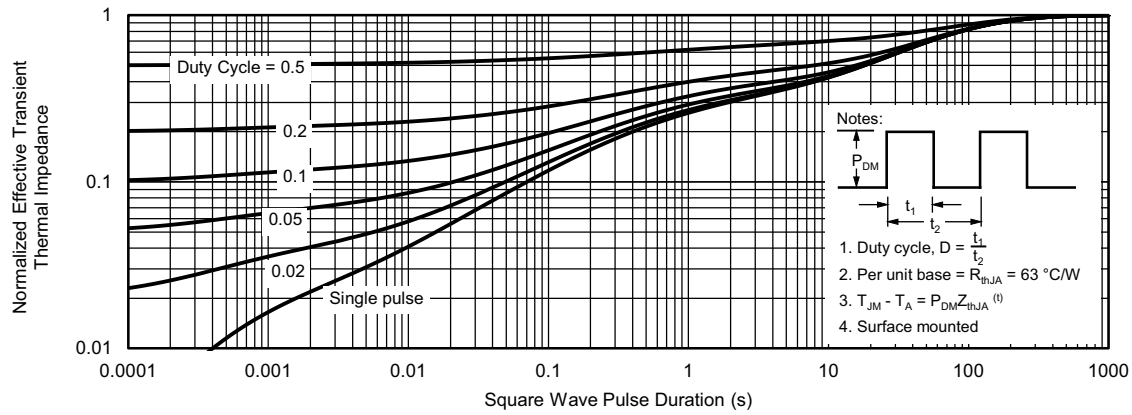
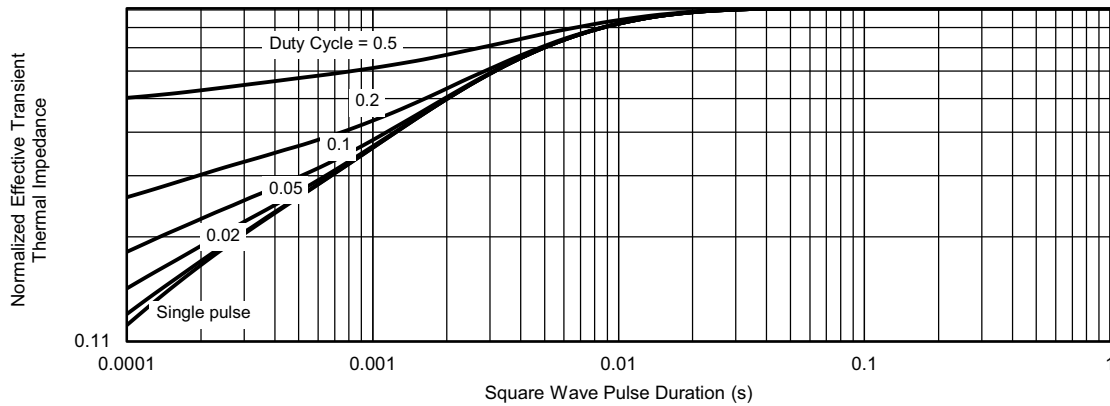


On-Resistance vs. Junction Temperature

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)**Source-Drain Diode Forward Voltage****Threshold Voltage****On-Resistance vs. Gate-to-Source Voltage****Single Pulse Power, Junction-to-Ambient****Safe Operating Area, Junction-to-Ambient**

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Current Derating ^a

Power, Junction-to-Case

Power, Junction-to-Ambient
Note

- a. The power dissipation P_D is based on $T_J \text{ max.} = 150^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Normalized Thermal Transient Impedance, Junction-to-Ambient

Normalized Thermal Transient Impedance, Junction-to-Case

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